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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM7®
Core Size	16/32-Bit
Speed	55MHz
Connectivity	I²C, SPI, SSC, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	32
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.65V ~ 1.95V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/at91sam7s64c-au

2. Block Diagram

Figure 2-1. SAM7S512/256/128/64/321/161 Block Diagram

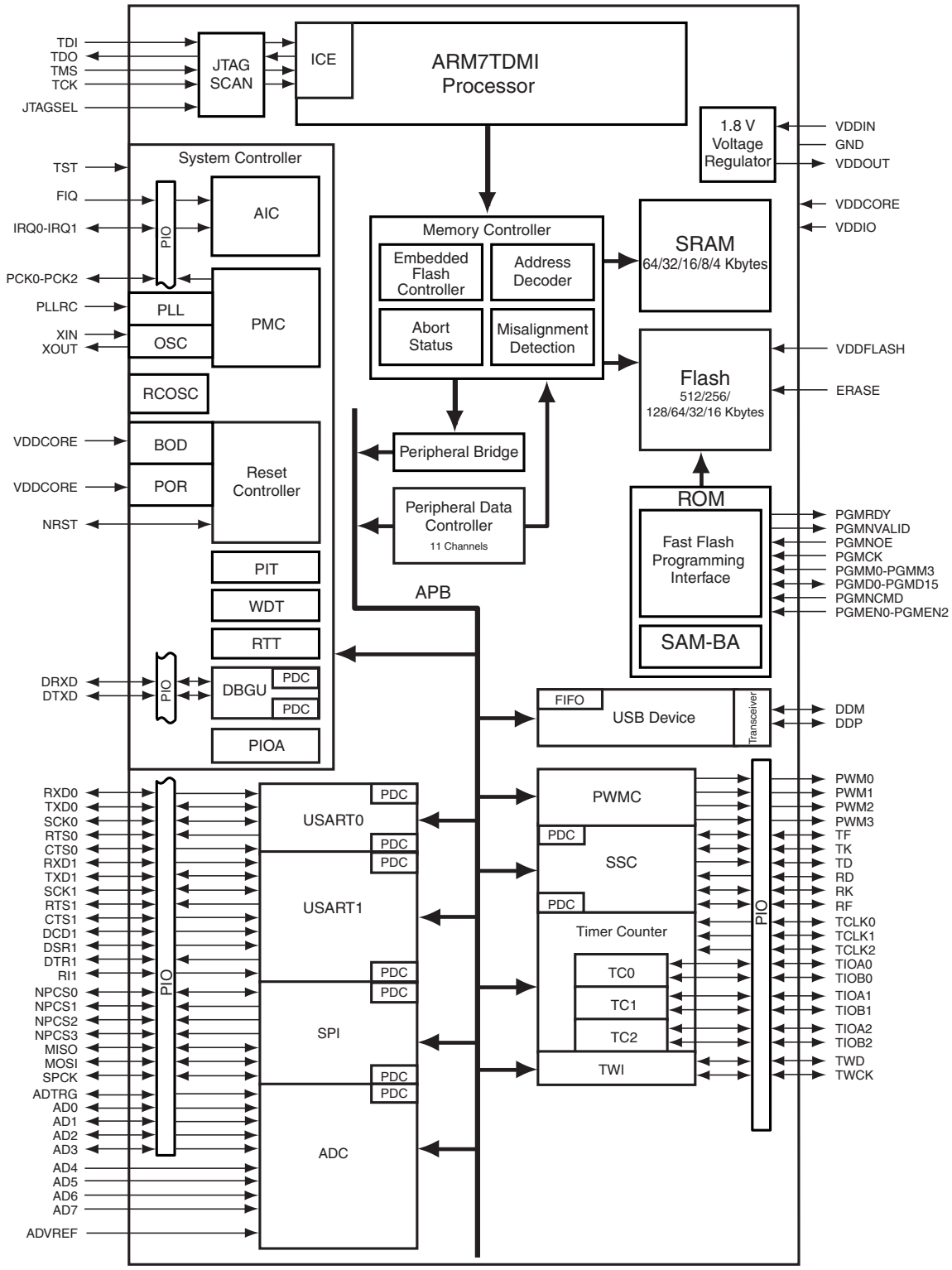


Figure 2-2. SAM7S32/16 Block Diagram

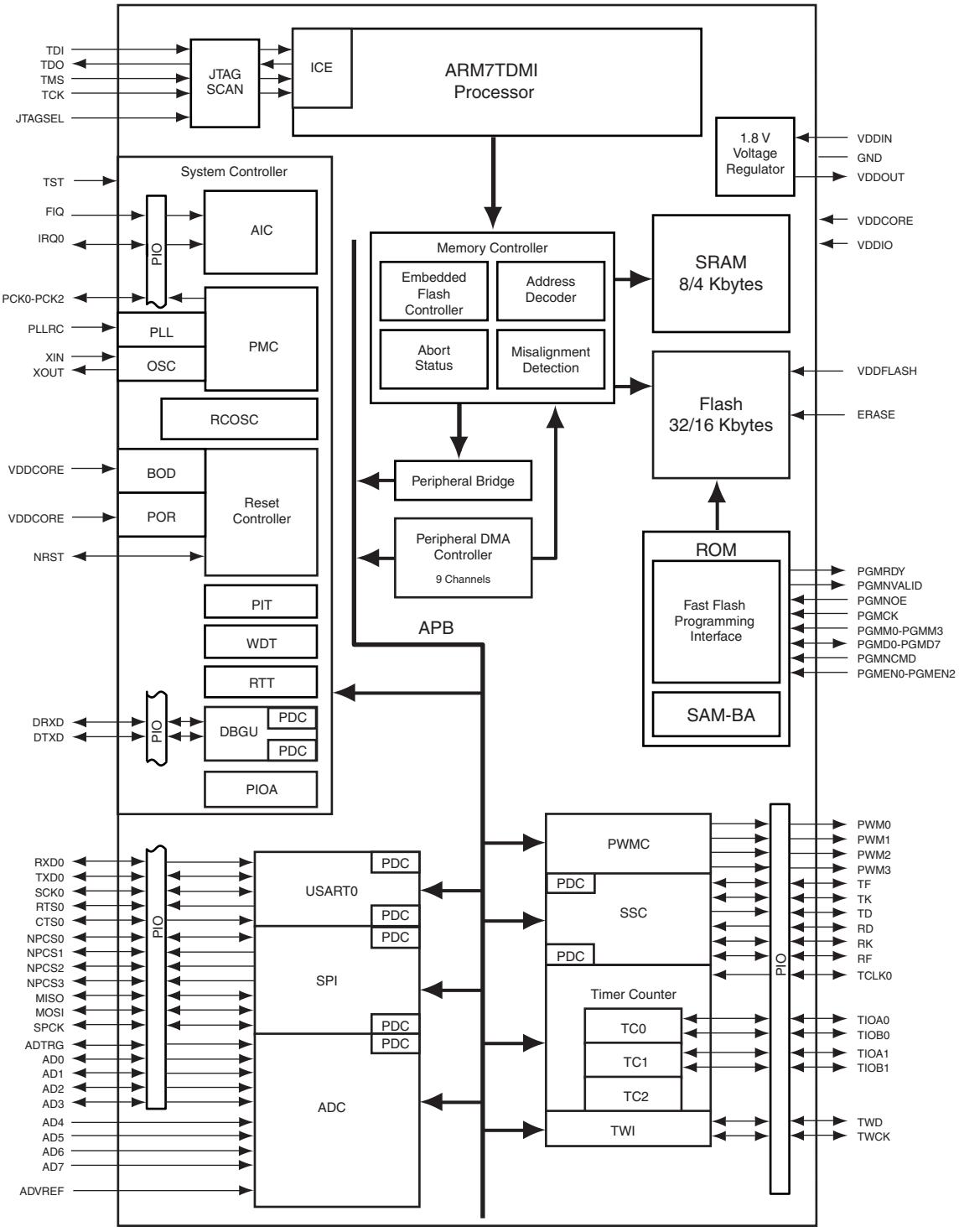


Table 3-1. Signal Description List (Continued)

DDM	USB Device Port Data -	Analog		not present on SAM7S32/16
DDP	USB Device Port Data +	Analog		not present on SAM7S32/16
SCK0 - SCK1	Serial Clock	I/O		SCK1 not present on SAM7S32/16
TXD0 - TXD1	Transmit Data	I/O		TXD1 not present on SAM7S32/16
RXD0 - RXD1	Receive Data	Input		RXD1 not present on SAM7S32/16
RTS0 - RTS1	Request To Send	Output		RTS1 not present on SAM7S32/16
CTS0 - CTS1	Clear To Send	Input		CTS1 not present on SAM7S32/16
DCD1	Data Carrier Detect	Input		not present on SAM7S32/16
DTR1	Data Terminal Ready	Output		not present on SAM7S32/16
DSR1	Data Set Ready	Input		not present on SAM7S32/16
RI1	Ring Indicator	Input		not present on SAM7S32/16
TD	Transmit Data	Output		
RD	Receive Data	Input		
TK	Transmit Clock	I/O		
RK	Receive Clock	I/O		
TF	Transmit Frame Sync	I/O		
RF	Receive Frame Sync	I/O		
TCLK0 - TCLK2	External Clock Inputs	Input		TCLK1 and TCLK2 not present on SAM7S32/16
TIOA0 - TIOA2	I/O Line A	I/O		TIOA2 not present on SAM7S32/16
TIOB0 - TIOB2	I/O Line B	I/O		TIOB2 not present on SAM7S32/16
PWM0 - PWM3	PWM Channels	Output		
MISO	Master In Slave Out	I/O		
MOSI	Master Out Slave In	I/O		
SPCK	SPI Serial Clock	I/O		
NPCS0	SPI Peripheral Chip Select 0	I/O	Low	
NPCS1-NPCS3	SPI Peripheral Chip Select 1 to 3	Output	Low	

4. Package and Pinout

The SAM7S512/256/128/64/321 are available in a 64-lead LQFP or 64-pad QFN package.

The SAM7S161 is available in a 64-Lead LQFP package.

The SAM7S32/16 are available in a 48-lead LQFP or 48-pad QFN package.

4.1 64-lead LQFP and 64-pad QFN Package Outlines

Figure 4-1 and Figure 4-2 show the orientation of the 64-lead LQFP and the 64-pad QFN package. A detailed mechanical description is given in the section Mechanical Characteristics of the full datasheet.

Figure 4-1. 64-lead LQFP Package (Top View)

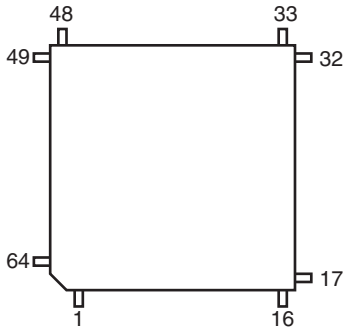


Figure 4-2. 64-pad QFN Package (Top View)

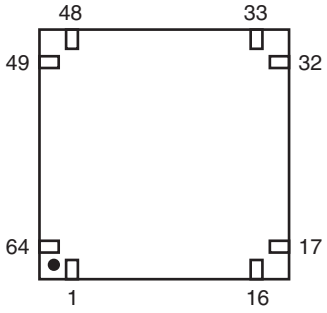
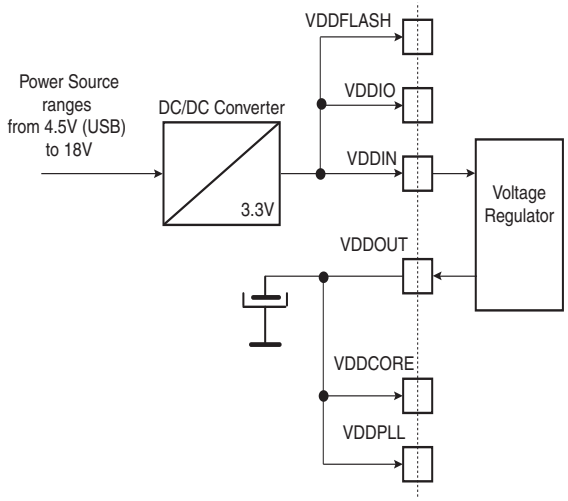


Figure 5-1. 3.3V System Single Power Supply Schematic



6. I/O Lines Considerations

6.1 JTAG Port Pins

TMS, TDI and TCK are schmitt trigger inputs. TMS and TCK are 5-V tolerant, TDI is not. TMS, TDI and TCK do not integrate a pull-up resistor.

TDO is an output, driven at up to VDDIO, and has no pull-up resistor.

The JTAGSEL pin is used to select the JTAG boundary scan when asserted at a high level. The JTAGSEL pin integrates a permanent pull-down resistor of about 15 kΩ to GND, so that it can be left unconnected for normal operations.

6.2 Test Pin

The TST pin is used for manufacturing test, fast programming mode or SAM-BA Boot Recovery of the SAM7S Series when asserted high. The TST pin integrates a permanent pull-down resistor of about 15 kΩ to GND, so that it can be left unconnected for normal operations.

To enter fast programming mode, the TST pin and the PA0 and PA1 pins should be tied high and PA2 tied to low.

To enter SAM-BA Boot Recovery, the TST pin and the PA0, PA1 and PA2 pins should be tied high for at least 10 seconds. Then a power cycle of the board is mandatory.

Driving the TST pin at a high level while PA0 or PA1 is driven at 0 leads to unpredictable results.

6.3 Reset Pin

The NRST pin is bidirectional with an open drain output buffer. It is handled by the on-chip reset controller and can be driven low to provide a reset signal to the external components or asserted low externally to reset the microcontroller. There is no constraint on the length of the reset pulse, and the reset controller can guarantee a minimum pulse length. This allows connection of a simple push-button on the pin NRST as system user reset, and the use of the signal NRST to reset all the components of the system.

The NRST pin integrates a permanent pull-up resistor to VDDIO.

6.4 ERASE Pin

The ERASE pin is used to re-initialize the Flash content and some of its NVM bits. It integrates a permanent pull-down resistor of about 15 kΩ to GND, so that it can be left unconnected for normal operations.

6.5 PIO Controller A Lines

- All the I/O lines PA0 to PA31on SAM7S512/256/128/64/321 (PA0 to PA20 on SAM7S32) are 5V-tolerant and all integrate a programmable pull-up resistor.
- All the I/O lines PA0 to PA31 on SAM7S161 (PA0 to PA20 on SAM7S16) are **not** 5V-tolerant and all integrate a programmable pull-up resistor.

Programming of this pull-up resistor is performed independently for each I/O line through the PIO controllers.

5V-tolerant means that the I/O lines can drive voltage level according to VDDIO, but can be driven with a voltage of up to 5.5V. However, driving an I/O line with a voltage over VDDIO while the programmable pull-up resistor is enabled will create a current path through the pull-up resistor from the I/O line to VDDIO. Care should be taken, in particular at reset, as all the I/O lines default to input with the pull-up resistor enabled at reset.

6.6 I/O Line Drive Levels

The PIO lines PA0 to PA3 are high-drive current capable. Each of these I/O lines can drive up to 16 mA permanently.

The remaining I/O lines can draw only 8 mA.

However, the total current drawn by all the I/O lines cannot exceed 150 mA (100 mA for SAM7S32/16).

7. Processor and Architecture

7.1 ARM7TDMI Processor

- RISC processor based on ARMv4T Von Neumann architecture
  - Runs at up to 55 MHz, providing 0.9 MIPS/MHz
- Two instruction sets
  - ARM® high-performance 32-bit instruction set
  - Thumb® high code density 16-bit instruction set
- Three-stage pipeline architecture
  - Instruction Fetch (F)
  - Instruction Decode (D)
  - Execute (E)

7.2 Debug and Test Features

- Integrated EmbeddedICE™ (embedded in-circuit emulator)
  - Two watchpoint units
  - Test access port accessible through a JTAG protocol
  - Debug communication channel
- Debug Unit
  - Two-pin UART
  - Debug communication channel interrupt handling
  - Chip ID Register
- IEEE1149.1 JTAG Boundary-scan on all digital pins

7.3 Memory Controller

- Bus Arbiter
  - Handles requests from the ARM7TDMI and the Peripheral DMA Controller
- Address decoder provides selection signals for
  - Three internal 1 Mbyte memory areas
  - One 256 Mbyte embedded peripheral area
- Abort Status Registers
  - Source, Type and all parameters of the access leading to an abort are saved
  - Facilitates debug by detection of bad pointers
- Misalignment Detector
  - Alignment checking of all data accesses
  - Abort generation in case of misalignment
- Remap Command
  - Remaps the SRAM in place of the embedded non-volatile memory
  - Allows handling of dynamic exception vectors
- Embedded Flash Controller
  - Embedded Flash interface, up to three programmable wait states
  - Prefetch buffer, buffering and anticipating the 16-bit requests, reducing the required wait states
  - Key-protected program, erase and lock/unlock sequencer
  - Single command for erasing, programming and locking operations
  - Interrupt generation in case of forbidden operation

- Fast access time, 30 MHz single-cycle access in Worst Case conditions
- Page programming time: 6 ms, including page auto-erase
- Page programming without auto-erase: 3 ms
- Full chip erase time: 15 ms
- 10,000 write cycles, 10-year data retention capability
- 16 lock bits, protecting 16 sectors of 32 pages
- Protection Mode to secure contents of the Flash

- 16 Kbytes of Fast SRAM
  - Single-cycle access at full speed

8.5 SAM7S321/32

- 32 Kbytes of Flash Memory, single plane
  - 256 pages of 128 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 8 lock bits, protecting 8 sectors of 32 pages
  - Protection Mode to secure contents of the Flash
- 8 Kbytes of Fast SRAM
  - Single-cycle access at full speed

8.6 SAM7S161/16

- 16 Kbytes of Flash Memory, single plane
  - 256 pages of 64 bytes
  - Fast access time, 30 MHz single-cycle access in Worst Case conditions
  - Page programming time: 6 ms, including page auto-erase
  - Page programming without auto-erase: 3 ms
  - Full chip erase time: 15 ms
  - 10,000 write cycles, 10-year data retention capability
  - 8 lock bits, protecting 8 sectors of 32 pages
  - Protection Mode to secure contents of the Flash
- 4 Kbytes of Fast SRAM
  - Single-cycle access at full speed

8.8.6 Calibration Bits

Eight NVM bits are used to calibrate the brownout detector and the voltage regulator. These bits are factory configured and cannot be changed by the user. The ERASE pin has no effect on the calibration bits.

8.9 Fast Flash Programming Interface

The Fast Flash Programming Interface allows programming the device through either a serial JTAG interface or through a multiplexed fully-handshaked parallel port. It allows gang-programming with market-standard industrial programmers.

The FFPI supports read, page program, page erase, full erase, lock, unlock and protect commands.

The Fast Flash Programming Interface is enabled and the Fast Programming Mode is entered when the TST pin and the PA0 and PA1 pins are all tied high and PA2 is tied low.

8.10 SAM-BA Boot Assistant

The SAM-BA® Boot Recovery restores the SAM-BA Boot in the first two sectors of the on-chip Flash memory. The SAM-BA Boot recovery is performed when the TST pin and the PA0, PA1 and PA2 pins are all tied high for 10 seconds. Then, a power cycle of the board is mandatory.

The SAM-BA Boot Assistant is a default Boot Program that provides an easy way to program in situ the on-chip Flash memory.

The SAM-BA Boot Assistant supports serial communication through the DBGU or through the USB Device Port. (The SAM7S32/16 have no USB Device Port.)

- Communication through the DBGU supports a wide range of crystals from 3 to 20 MHz via software auto-detection.
- Communication through the USB Device Port is limited to an 18.432 MHz crystal. (

The SAM-BA Boot provides an interface with SAM-BA Graphic User Interface (GUI).

9. System Controller

The System Controller manages all vital blocks of the microcontroller: interrupts, clocks, power, time, debug and reset.

The System Controller peripherals are all mapped to the highest 4 Kbytes of address space, between addresses 0xFFFF F000 and 0xFFFF FFFF.

Figure 9-1 on page 26 and Figure 9-2 on page 27 show the product specific System Controller Block Diagrams.

Figure 8-1 on page 20 shows the mapping of the of the User Interface of the System Controller peripherals. Note that the memory controller configuration user interface is also mapped within this address space.

Figure 9-1. System Controller Block Diagram (SAM7S512/256/128/64/321/161)

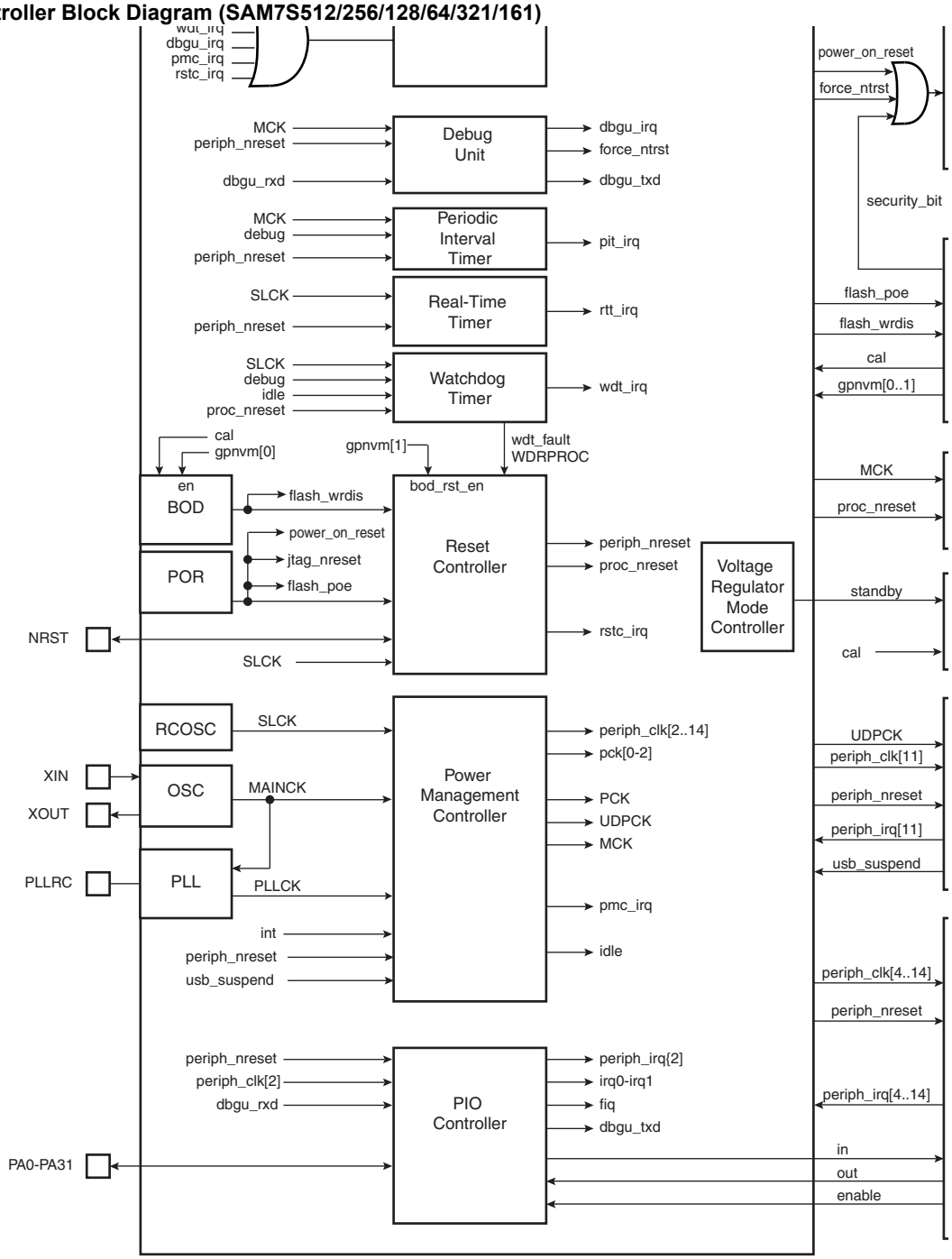
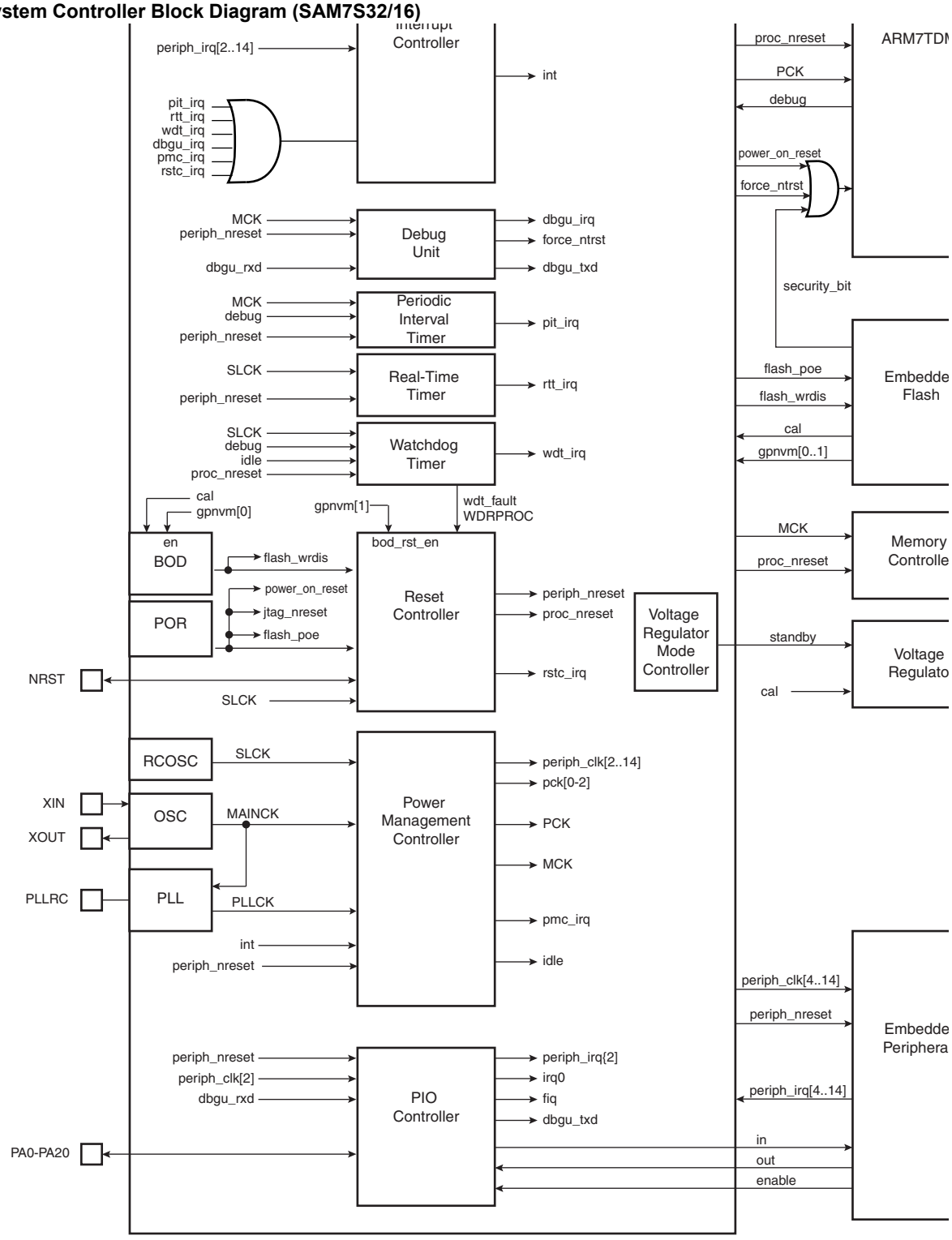


Figure 9-2. System Controller Block Diagram (SAM7S32/16)



9.1 Reset Controller

The Reset Controller is based on a power-on reset cell and one brownout detector. It gives the status of the last reset, indicating whether it is a power-up reset, a software reset, a user reset, a watchdog reset or a brownout reset. In addition, it controls the internal resets and the NRST pin open-drain output. It allows to shape a signal on the NRST line, guaranteeing that the length of the pulse meets any requirement.

Note that if NRST is used as a reset output signal for external devices during power-off, the brownout detector must be activated.

9.1.1 Brownout Detector and Power-on Reset

The SAM7S Series embeds a brownout detection circuit and a power-on reset cell. Both are supplied with and monitor VDDCORE. Both signals are provided to the Flash to prevent any code corruption during power-up or power-down sequences or if brownouts occur on the VDDCORE power supply.

The power-on reset cell has a limited-accuracy threshold at around 1.5V. Its output remains low during power-up until VDDCORE goes over this voltage level. This signal goes to the reset controller and allows a full re-initialization of the device.

The brownout detector monitors the VDDCORE level during operation by comparing it to a fixed trigger level. It secures system operations in the most difficult environments and prevents code corruption in case of brownout on the VDDCORE.

Only VDDCORE is monitored.

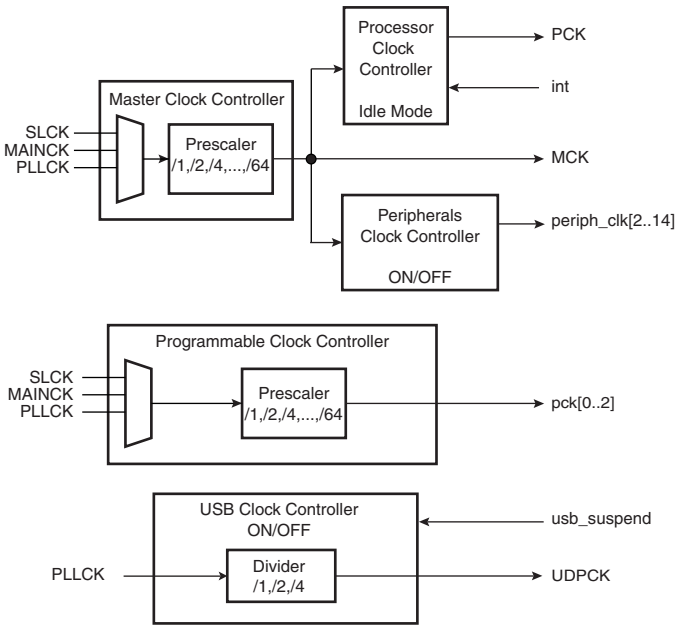
When the brownout detector is enabled and VDDCORE decreases to a value below the trigger level (Vbot-, defined as Vbot - hyst/2), the brownout output is immediately activated.

When VDDCORE increases above the trigger level (Vbot+, defined as Vbot + hyst/2), the reset is released. The brownout detector only detects a drop if the voltage on VDDCORE stays below the threshold voltage for longer than about 1µs.

The threshold voltage has a hysteresis of about 50 mV, to ensure spike free brownout detection. The typical value of the brownout detector threshold is 1.68V with an accuracy of ± 2% and is factory calibrated.

The brownout detector is low-power, as it consumes less than 20 µA static current. However, it can be deactivated to save its static current. In this case, it consumes less than 1µA. The deactivation is configured through the GPNVM bit 0 of the Flash.

Figure 9-4. Power Management Controller Block Diagram



9.4 Advanced Interrupt Controller

- Controls the interrupt lines (nIRQ and nFIQ) of an ARM Processor
- Individually maskable and vectored interrupt sources
  - Source 0 is reserved for the Fast Interrupt Input (FIQ)
  - Source 1 is reserved for system peripherals RTT, PIT, EFC, PMC, DBGU, etc.)
  - Other sources control the peripheral interrupts or external interrupts
  - Programmable edge-triggered or level-sensitive internal sources
  - Programmable positive/negative edge-triggered or high/low level-sensitive external sources
- 8-level Priority Controller
  - Drives the normal interrupt of the processor
  - Handles priority of the interrupt sources
  - Higher priority interrupts can be served during service of lower priority interrupt
- Vectoring
  - Optimizes interrupt service routine branch and execution
  - One 32-bit vector register per interrupt source
  - Interrupt vector register reads the corresponding current interrupt vector
- Protect Mode
  - Easy debugging by preventing automatic operations
- Fast Forcing
  - Permits redirecting any interrupt source on the fast interrupt
- General Interrupt Mask
  - Provides processor synchronization on events without triggering an interrupt

9.5 Debug Unit

- Comprises:
  - One two-pin UART
  - One Interface for the Debug Communication Channel (DCC) support

- One set of Chip ID Registers
- One Interface providing ICE Access Prevention

- Two-pin UART
  - Implemented features are compatible with the USART
  - Programmable Baud Rate Generator
  - Parity, Framing and Overrun Error
  - Automatic Echo, Local Loopback and Remote Loopback Channel Modes
- Debug Communication Channel Support
  - Offers visibility of COMMRX and COMMTX signals from the ARM Processor
- Chip ID Registers
  - Identification of the device revision, sizes of the embedded memories, set of peripherals
  - Chip ID is 0x270B0A40 for AT91SAM7S512 Rev A
  - Chip ID is 0x270B0A4F for AT91SAM7S512 Rev B
  - Chip ID is 0x270D0940 for AT91SAM7S256 Rev A
  - Chip ID is 0x270B0941 for AT91SAM7S256 Rev B
  - Chip ID is 0x270B0942 for AT91SAM7S256 Rev C
  - Chip ID is TBD for AT91SAM7S256 Rev D
  - Chip ID is 0x270C0740 for AT91SAM7S128 Rev A
  - Chip ID is 0x270A0741 for AT91SAM7S128 Rev B
  - Chip ID is 0x270A0742 for AT91SAM7S128 Rev C
  - Chip ID is TBD for AT91SAM7S128 Rev D
  - Chip ID is 0x27090540 for AT91SAM7S64 Rev A
  - Chip ID is 0x27090543 for AT91SAM7S64 Rev B
  - Chip ID is 0x27090544 for AT91SAM7S64 Rev C
  - Chip ID is 0x27080342 for AT91SAM7S321 Rev A
  - Chip ID is 0x27080340 for AT91SAM7S32 Rev A
  - Chip ID is 0x27080341 for AT91SAM7S32 Rev B
  - Chip ID is 0x27050241 for AT9SAM7S161 Rev A
  - Chip ID is 0x27050240 for AT91SAM7S16 Rev A

Note: Refer to the errata section of the datasheet for updates on chip ID.

9.6 Periodic Interval Timer

- 20-bit programmable counter plus 12-bit interval counter

9.7 Watchdog Timer

- 12-bit key-protected Programmable Counter running on prescaled SCLK
- Provides reset or interrupt signals to the system
- Counter may be stopped while the processor is in debug state or in idle mode

9.8 Real-time Timer

- 32-bit free-running counter with alarm running on prescaled SCLK
- Programmable 16-bit prescaler for SLCK accuracy compensation

10.4 PIO Controller A Multiplexing

Table 10-3. Multiplexing on PIO Controller A (SAM7S512/256/128/64/321/161)

PA0	PWM0	TIOA0	High-Drive		
PA1	PWM1	TIOB0	High-Drive		
PA2	PWM2	SCK0	High-Drive		
PA3	TWD	NPCS3	High-Drive		
PA4	TWCK	TCLK0			
PA5	RXD0	NPCS3			
PA6	TXD0	PCK0			
PA7	RTS0	PWM3			
PA8	CTS0	ADTRG			
PA9	DRXD	NPCS1			
PA10	DTXD	NPCS2			
PA11	NPCS0	PWM0			
PA12	MISO	PWM1			
PA13	MOSI	PWM2			
PA14	SPCK	PWM3			
PA15	TF	TIOA1			
PA16	TK	TIOB1			
PA17	TD	PCK1	AD0		
PA18	RD	PCK2	AD1		
PA19	RK	FIQ	AD2		
PA20	RF	IRQ0	AD3		
PA21	RXD1	PCK1			
PA22	TXD1	NPCS3			
PA23	SCK1	PWM0			
PA24	RTS1	PWM1			
PA25	CTS1	PWM2			
PA26	DCD1	TIOA2			
PA27	DTR1	TIOB2			
PA28	DSR1	TCLK1			
PA29	RI1	TCLK2			
PA30	IRQ1	NPCS2			
PA31	NPCS1	PCK2			

10.5 Serial Peripheral Interface

- Supports communication with external serial devices
  - Four chip selects with external decoder allow communication with up to 15 peripherals
  - Serial memories, such as DataFlash® and 3-wire EEPROMs
  - Serial peripherals, such as ADCs, DACs, LCD Controllers, CAN Controllers and Sensors
  - External co-processors
- Master or slave serial peripheral bus interface
  - 8- to 16-bit programmable data length per chip select
  - Programmable phase and polarity per chip select
  - Programmable transfer delays between consecutive transfers and between clock and data per chip select
  - Programmable delay between consecutive transfers
  - Selectable mode fault detection
  - Maximum frequency at up to Master Clock

10.6 Two-wire Interface

- Master Mode only (SAM7S512/256/128/64/321/32)
- Master, Multi-Master and Slave Mode support (SAM7S161/16)
- General Call supported in Slave Mode (SAM7S161/16)
- Compatibility with I^2C compatible devices (refer to the TWI sections of the datasheet)
- One, two or three bytes internal address registers for easy Serial Memory access
- 7-bit or 10-bit slave addressing
- Sequential read/write operations

10.7 USART

- Programmable Baud Rate Generator
- 5- to 9-bit full-duplex synchronous or asynchronous serial communications
  - 1, 1.5 or 2 stop bits in Asynchronous Mode
  - 1 or 2 stop bits in Synchronous Mode
  - Parity generation and error detection
  - Framing error detection, overrun error detection
  - MSB or LSB first
  - Optional break generation and detection
  - By 8 or by 16 over-sampling receiver frequency
  - Hardware handshaking RTS - CTS
  - Modem Signals Management DTR-DSR-DCD-RI on USART1 (not present on SAM7S32/16)
  - Receiver time-out and transmitter timeguard
  - Multi-drop Mode with address generation and detection
- RS485 with driver control signal
- ISO7816, T = 0 or T = 1 Protocols for interfacing with smart cards
  - NACK handling, error counter with repetition and iteration limit
- IrDA modulation and demodulation
  - Communication at up to 115.2 Kbps
- Test Modes
  - Remote Loopback, Local Loopback, Automatic Echo

10.8 Serial Synchronous Controller

- Provides serial synchronous communication links used in audio and telecom applications
- Contains an independent receiver and transmitter and a common clock divider
- Offers a configurable frame sync and data length
- Receiver and transmitter can be programmed to start automatically or on detection of different event on the frame sync signal
- Receiver and transmitter include a data signal, a clock signal and a frame synchronization signal

10.9 Timer Counter

- Three 16-bit Timer Counter Channels
  - Two output compare or one input capture per channel (except for SAM7S32/16 which have only two channels connected to the PIO)
- Wide range of functions including:
  - Frequency measurement
  - Event counting
  - Interval measurement
  - Pulse generation
  - Delay timing
  - Pulse Width Modulation
  - Up/down capabilities
- Each channel is user-configurable and contains:
  - Three external clock inputs (The SAM7S32/16 have one)
  - Five internal clock inputs, as defined in Table 10-5

Table 10-5. Timer Counter Clocks Assignment

TIMER_CLOCK1	MCK/2
TIMER_CLOCK2	MCK/8
TIMER_CLOCK3	MCK/32
TIMER_CLOCK4	MCK/128
TIMER_CLOCK5	MCK/1024

  - Two multi-purpose input/output signals
  - Two global registers that act on all three TC channels

10.10 PWM Controller

- Four channels, one 16-bit counter per channel
- Common clock generator, providing thirteen different clocks
  - One Modulo n counter providing eleven clocks
  - Two independent linear dividers working on modulo n counter outputs
- Independent channel programming
  - Independent enable/disable commands
  - Independent clock selection
  - Independent period and duty cycle, with double buffering
  - Programmable selection of the output waveform polarity

11. Package Drawings

The SAM7S series devices are available in LQFP and QFN package types.

11.1 LQFP Packages

Figure 11-1. 48-and 64-lead LQFP Package Drawing

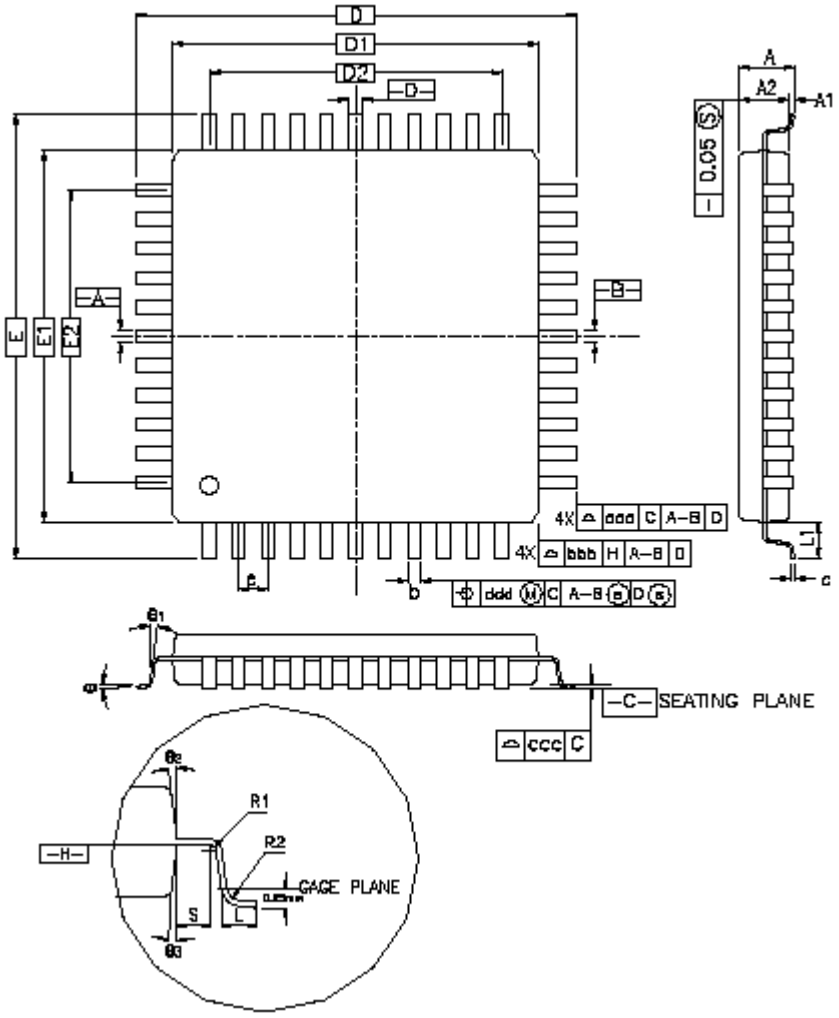


Table 11-2. 64-lead LQFP Package Dimensions (in mm)

Symbol						
A	–	–	1.60	–	–	0.063
A1	0.05	–	0.15	0.002	–	0.006
A2	1.35	1.40	1.45	0.053	0.055	0.057
D	12.00 BSC			0.472 BSC		
D1	10.00 BSC			0.383 BSC		
E	12.00 BSC			0.472 BSC		
E1	10.00 BSC			0.383 BSC		
R2	0.08	–	0.20	0.003	–	0.008
R1	0.08	–	–	0.003	–	–
q	0°	3.5°	7°	0°	3.5°	7°
θ_1	0°	–	–	0°	–	–
θ_2	11°	12°	13°	11°	12°	13°
θ_3	11°	12°	13°	11°	12°	13°
c	0.09	–	0.20	0.004	–	0.008
L	0.45	0.60	0.75	0.018	0.024	0.030
L1	1.00 REF			0.039 REF		
S	0.20	–	–	0.008	–	–
b	0.17	0.20	0.27	0.007	0.008	0.011
e	0.50 BSC.			0.020 BSC.		
D2	7.50			0.285		
E2	7.50			0.285		
Tolerances of Form and Position						
aaa	0.20			0.008		
bbb	0.20			0.008		
ccc	0.08			0.003		
ddd	0.08			0.003		

Figure 11-3. 64-pad QFN Package Drawing